

HEF4067B-Q100

16-channel analog multiplexer/demultiplexer

Rev. 2 — 11 September 2014

Product data sheet

1. General description

The HEF4067B-Q100 is a 16-channel analog multiplexer/demultiplexer. It has four address inputs (A0 to A3), an active LOW enable input (\bar{E}), 16 independent inputs/outputs (Y0 to Y15) and a common input/output (Z). The device contains 16 bidirectional analog switches. Each switch has one side connected to an independent input/output (Y0 to Y15) and the other side connected to the common input/output (Z). With \bar{E} LOW, one of the 16 switches is selected (low-impedance ON-state) by A0 to A3. All unselected switches are in the high-impedance OFF-state. With \bar{E} HIGH all switches are in the high-impedance OFF-state, independent of A0 to A3. The analog inputs/outputs (Y0 to Y15 and Z) can swing between V_{DD} as a positive limit and V_{SS} as a negative limit. V_{DD} to V_{SS} may not exceed 15 V.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 3) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 3)
 - ◆ Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$
- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0 Ω)
- Complies with JEDEC standard JESD 13-B

3. Applications

- Analog multiplexing and demultiplexing
- Digital multiplexing and demultiplexing
- Signal gating



4. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
HEF4067BT-Q100	-40 °C to +85 °C	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1

5. Functional diagram

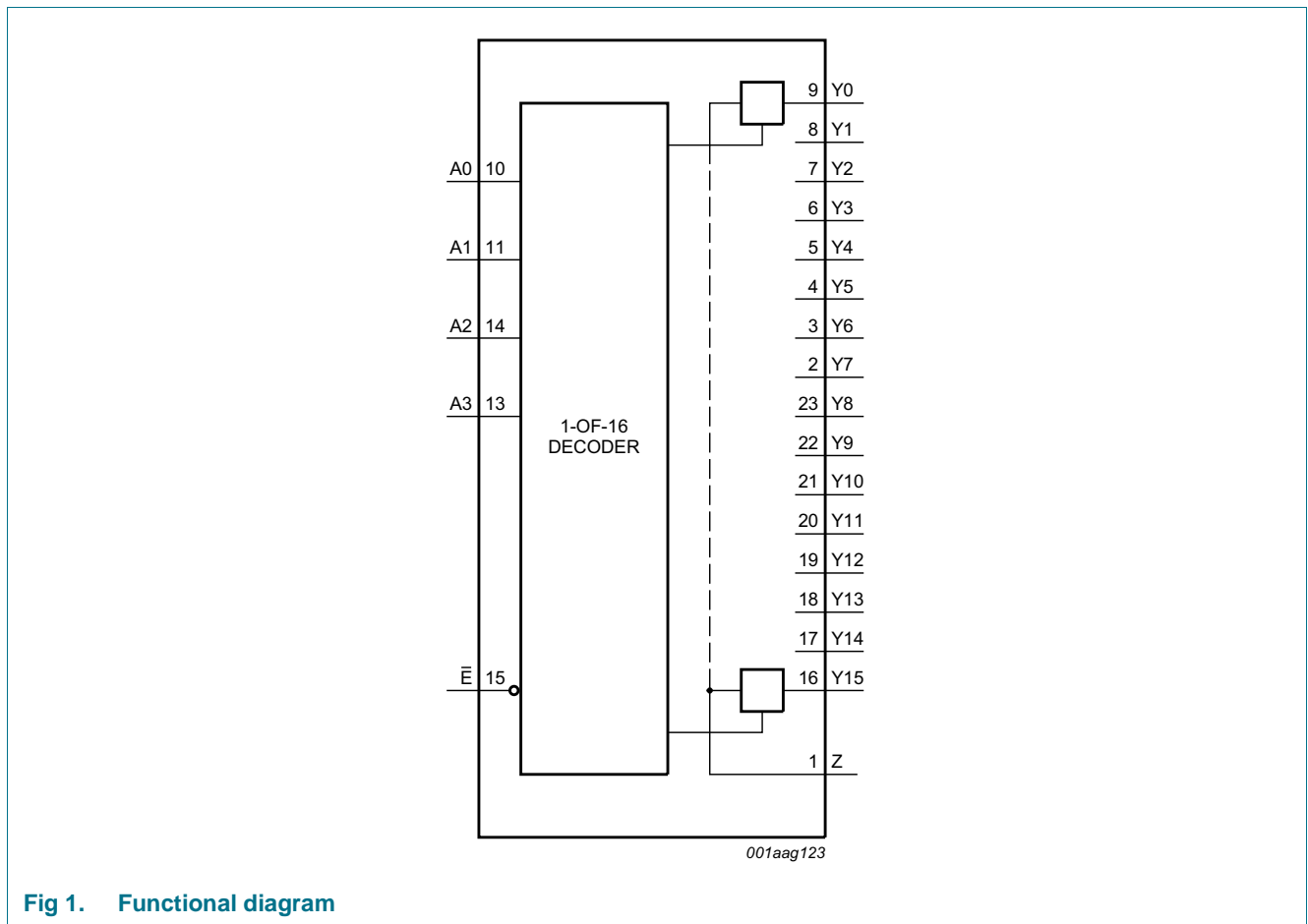


Fig 1. Functional diagram

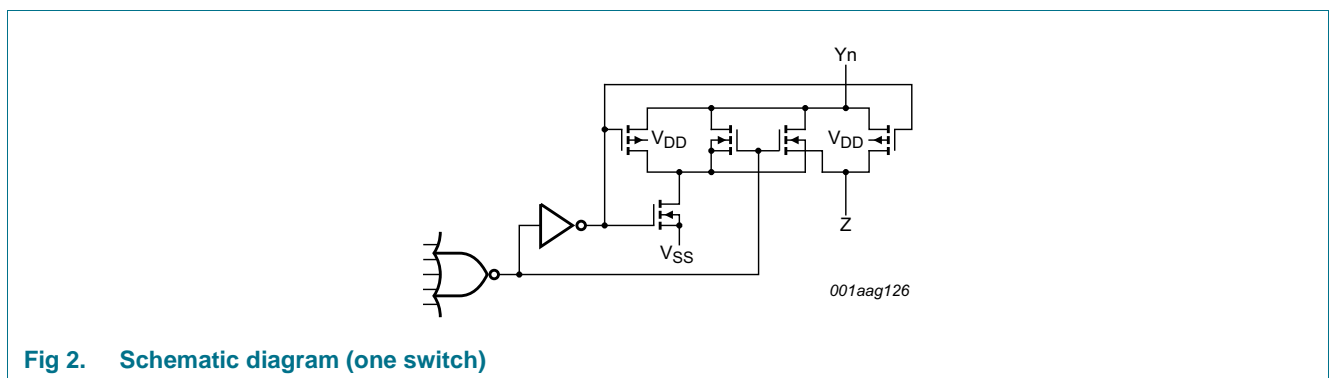


Fig 2. Schematic diagram (one switch)

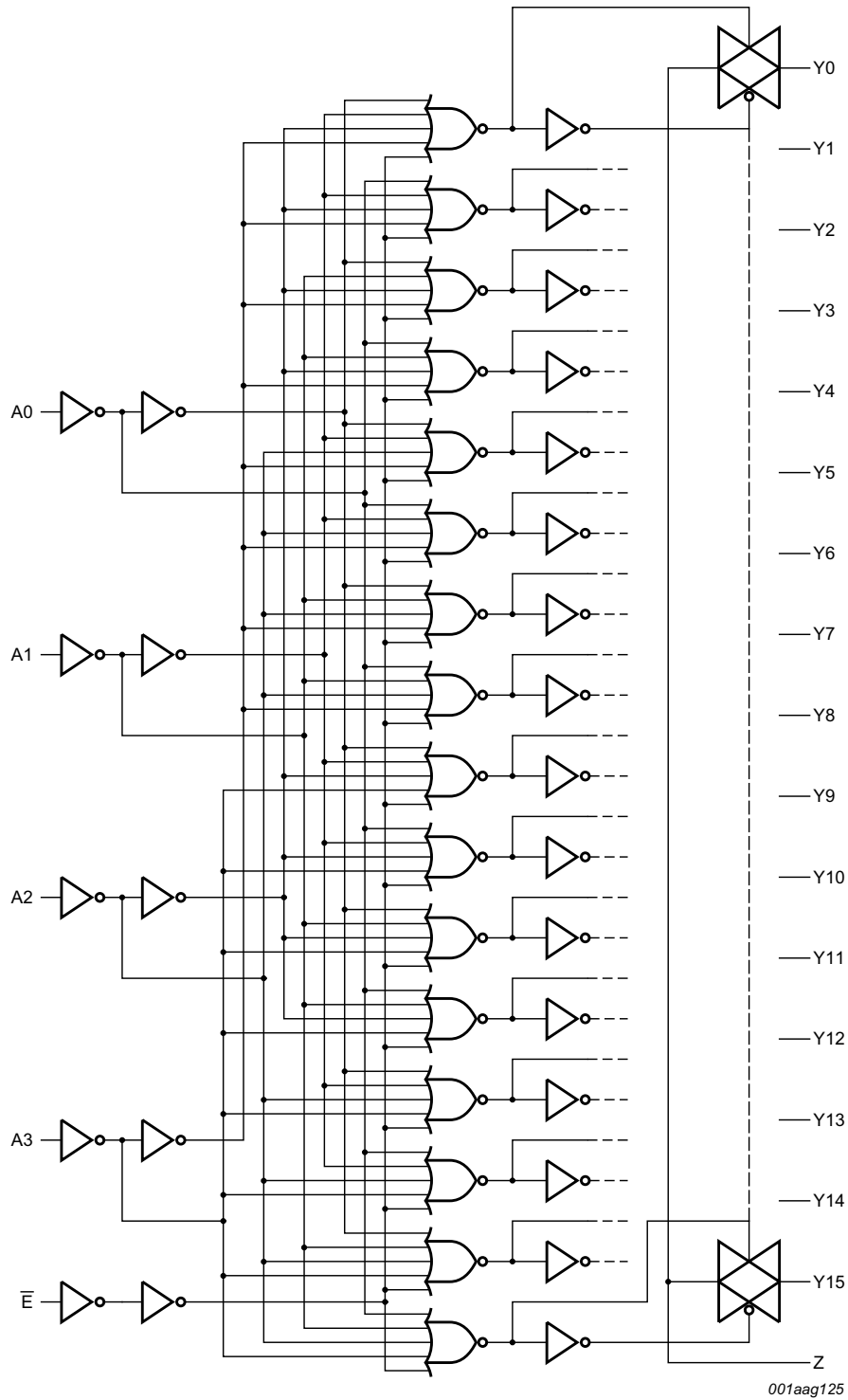
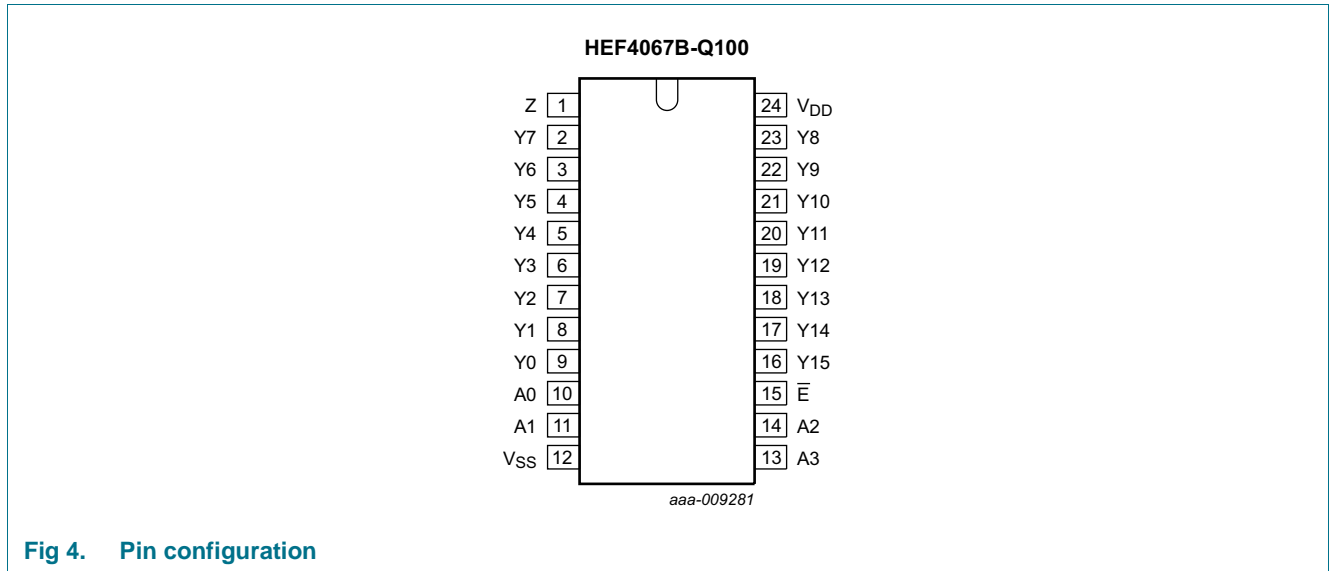


Fig 3. Logic diagram

6. Pinning information

6.1 Pinning



6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
Z	1	common input/output
Y0 to Y15	9, 8, 7, 6, 5, 4, 3, 2, 23, 22, 21, 20, 19, 18, 17, 16	independent input/output
A0 to A3	10, 11, 14, 13	address input
V _{SS}	12	ground (0 V)
\bar{E}	15	enable input (active LOW)
V _{DD}	24	supply voltage

7. Functional description

Table 3. Function table^[1]

Control	Address				Channel ON
	A3	A2	A1	A0	
\bar{E}					
L	L	L	L	L	Y0 = Z
L	L	L	L	H	Y1 = Z
L	L	L	H	L	Y2 = Z
L	L	L	H	H	Y3 = Z
L	L	H	L	L	Y4 = Z
L	L	H	L	H	Y5 = Z
L	L	H	H	L	Y6 = Z
L	L	H	H	H	Y7 = Z
L	H	L	L	L	Y8 = Z
L	H	L	L	H	Y9 = Z
L	H	L	H	L	Y10 = Z
L	H	L	H	H	Y11 = Z
L	H	H	L	L	Y12 = Z
L	H	H	L	H	Y13 = Z
L	H	H	H	L	Y14 = Z
L	H	H	H	H	Y15 = Z
H	X	X	X	X	none

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to $V_{SS} = 0$ V (ground).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DD}	supply voltage		-0.5	+18	V
I_{IK}	input clamping current	pins An and \bar{E} ; $V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V	-	± 10	mA
V_I	input voltage		-0.5	$V_{DD} + 0.5$	V
$I_{I/O}$	input/output current		[1] -	± 10	mA
I_{DD}	supply current		-	50	mA
T_{stg}	storage temperature		-65	+150	°C
T_{amb}	ambient temperature		-40	+85	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[2] -	500	mW
P	power dissipation	per output	-	100	mW

[1] To avoid drawing V_{DD} current from terminal Z, when switch current flows into terminals Yn, the voltage drop across the bidirectional switch must not exceed 0.4 V. If the switch current flows into terminal Z, no V_{DD} current flows from terminals Yn. In this case, there is no limit for the voltage drop across the switch, but the voltages at Y and Z may not exceed V_{DD} or V_{SS} .

[2] For SO24 packages: above $T_{amb} = 70$ °C, P_{tot} derates linearly at 8 mW/K.

9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DD}	supply voltage		3	-	15	V
V_I	input voltage		0	-	V_{DD}	V
T_{amb}	ambient temperature	in free air	-40	-	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5\text{ V}$	-	-	3.75	$\mu\text{s/V}$
		$V_{DD} = 10\text{ V}$	-	-	0.5	$\mu\text{s/V}$
		$V_{DD} = 15\text{ V}$	-	-	0.08	$\mu\text{s/V}$

10. Static characteristics

Table 6. Static characteristics

$V_{SS} = 0\text{ V}$; $V_I = V_{SS}$ or V_{DD} ; unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	$T_{amb} = -40\text{ °C}$		$T_{amb} = +25\text{ °C}$		$T_{amb} = +85\text{ °C}$		Unit
				Min	Max	Min	Max	Min	Max	
V_{IL}	LOW-level input voltage	$ I_O < 1\ \mu\text{A}$								
		$V_O = 0.5\text{ V or }4.5\text{ V}$	5 V	-	1	-	1	-	1	V
		$V_O = 1.0\text{ V or }9.0\text{ V}$	10 V	-	2	-	2	-	2	V
		$V_O = 1.5\text{ V or }13.5\text{ V}$	15 V	-	2.5	-	2.5	-	2.5	V
V_{IH}	HIGH-level input voltage	$ I_O < 1\ \mu\text{A}$								
		$V_O = 0.5\text{ V or }4.5\text{ V}$	5 V	4	-	4	-	4	-	V
		$V_O = 1.0\text{ V or }9.0\text{ V}$	10 V	8	-	8	-	8	-	V
		$V_O = 1.5\text{ V or }13.5\text{ V}$	15 V	12.5	-	12.5	-	12.5	-	V
I_I	input leakage current	$V_I = 0\text{ V or }15\text{ V}$	15 V	-	± 0.3	-	± 0.3	-	± 1.0	μA
I_{OZ}	OFF-state output current	output at V_{DD}	15 V	-	1.6	-	1.6	-	12.0	μA
		output at V_{SS}	15 V	-	-1.6	-	-1.6	-	-12.0	μA
$I_{S(OFF)}$	OFF-state leakage current	Z port; all channels OFF; see Figure 5	15 V	-	-	-	1000	-	-	nA
		Yn port; per channel; see Figure 6	15 V	-	-	-	200	-	-	nA
I_{DD}	supply current	all valid input combinations; $I_O = 0\text{ A}$	5 V	-	20	-	20	-	150	μA
			10 V	-	40	-	40	-	300	μA
			15 V	-	80	-	80	-	600	μA
C_I	input capacitance	digital inputs	15 V	-	-	-	7.5	-	-	pF

10.1 Test circuits

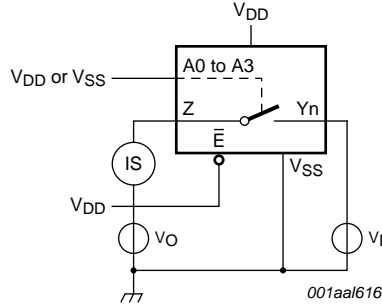


Fig 5. Test circuit for measuring OFF-state leakage current Z port

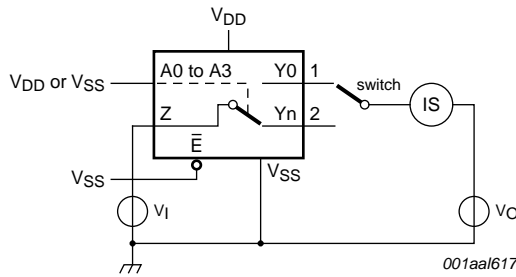


Fig 6. Test circuit for measuring OFF-state leakage current Yn port

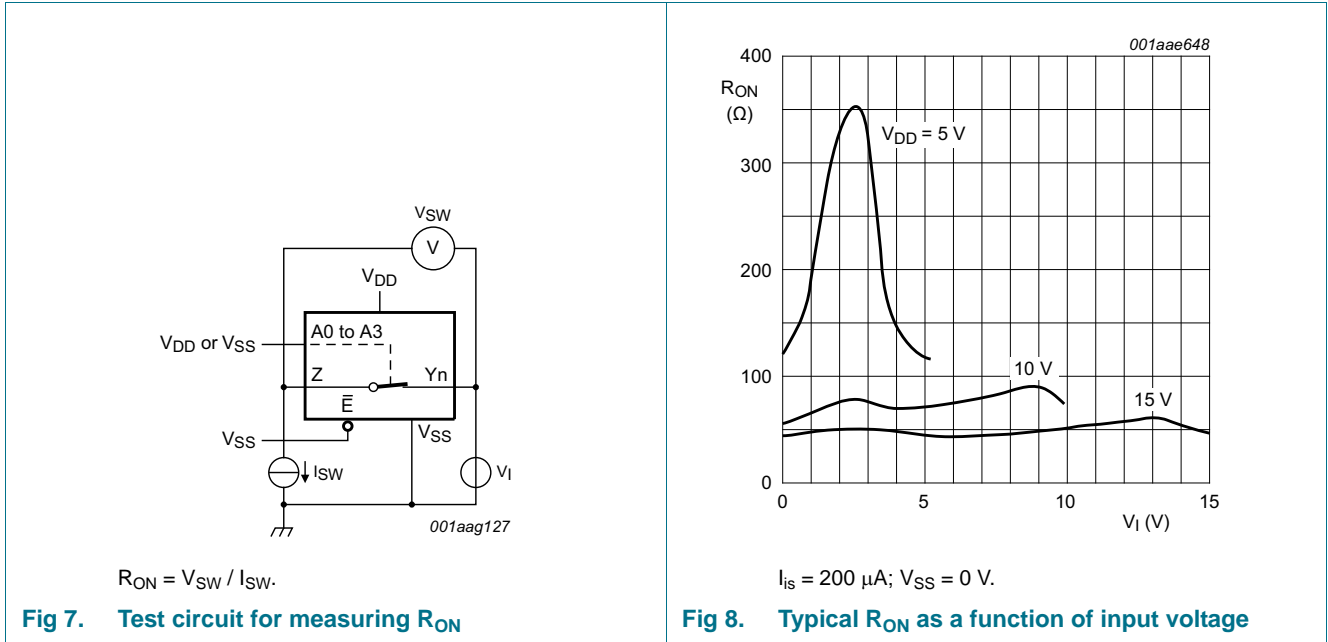
10.2 On resistance

Table 7. ON resistance

$T_{amb} = 25\text{ }^{\circ}\text{C}$; $I_{SW} = 200\text{ }\mu\text{A}$; $V_{SS} = 0\text{ V}$.

Symbol	Parameter	Conditions	V _{DD}	Typ	Max	Unit
R _{ON(peak)}	ON resistance (peak)	$V_I = 0\text{ V to }V_{DD}$; see Figure 7 and Figure 8	5 V	350	2500	Ω
			10 V	80	245	Ω
			15 V	60	175	Ω
R _{ON(rail)}	ON resistance (rail)	$V_I = 0\text{ V}$; see Figure 7 and Figure 8	5 V	115	340	Ω
			10 V	50	160	Ω
			15 V	40	115	Ω
		$V_I = V_{DD}$; see Figure 7 and Figure 8	5 V	120	365	Ω
			10 V	65	200	Ω
			15 V	50	155	Ω
ΔR_{ON}	ON resistance mismatch between channels	$V_I = 0\text{ V to }V_{DD}$; see Figure 7	5 V	25	-	Ω
			10 V	10	-	Ω
			15 V	5	-	Ω

10.2.1 On resistance waveform and test circuit



11. Dynamic characteristics

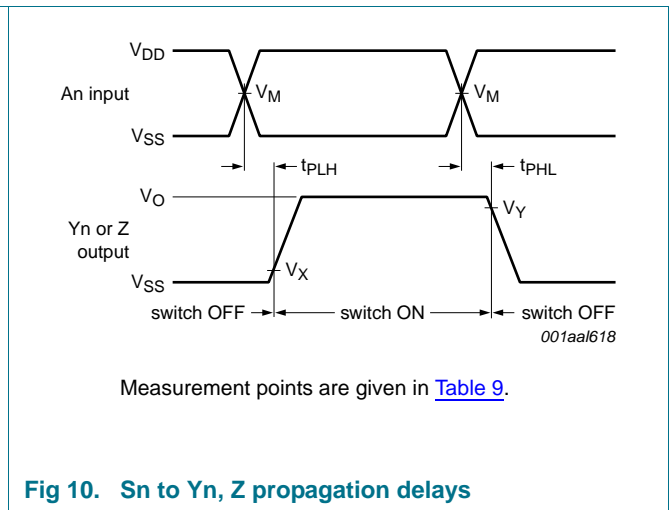
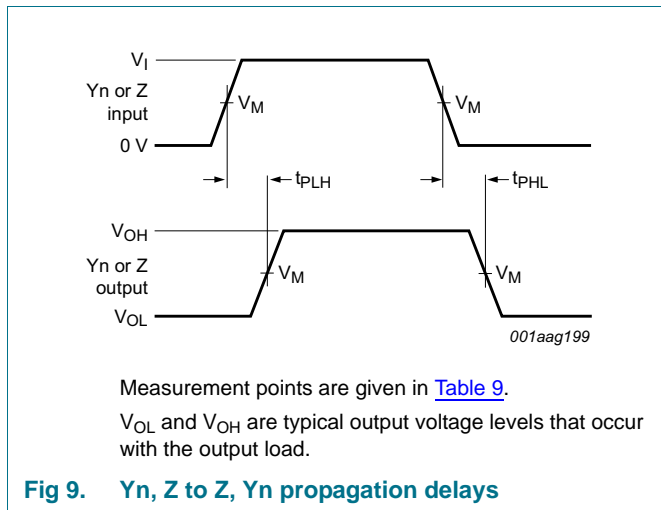
Table 8. Dynamic characteristics
 $T_{amb} = 25 \text{ }^\circ\text{C}; V_{SS} = 0 \text{ V};$ for test circuit, see [Figure 12](#).

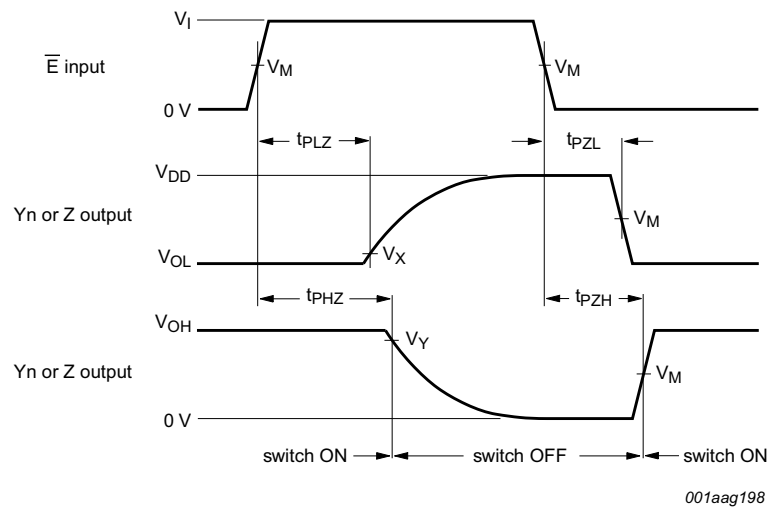
Symbol	Parameter	Conditions	V_{DD}	Min	Typ	Max	Unit
t_{PHL}	HIGH to LOW propagation delay	Y_n, Z to Z, Y_n ; see Figure 9	5 V	-	30	60	ns
			10 V	-	15	25	ns
			15 V	-	10	20	ns
		A_n to Y_n, Z ; see Figure 10	5 V	-	190	380	ns
			10 V	-	70	145	ns
			15 V	-	50	100	ns
t_{PLH}	LOW to HIGH propagation delay	Y_n, Z to Z, Y_n ; see Figure 9	5 V	-	25	50	ns
			10 V	-	10	20	ns
			15 V	-	10	20	ns
		A_n to Y_n, Z ; see Figure 10	5 V	-	175	345	ns
			10 V	-	70	140	ns
			15 V	-	50	100	ns
t_{PHZ}	HIGH to OFF-state propagation delay	\bar{E} to Y_n, Z ; see Figure 11	5 V	-	195	385	ns
			10 V	-	140	280	ns
			15 V	-	130	260	ns
t_{PLZ}	LOW to OFF-state propagation delay	\bar{E} to Y_n, Z ; see Figure 11	5 V	-	215	435	ns
			10 V	-	180	355	ns
			15 V	-	170	340	ns

Table 8. Dynamic characteristics ...continued
 $T_{amb} = 25\text{ }^{\circ}\text{C}$; $V_{SS} = 0\text{ V}$; for test circuit, see [Figure 12](#).

Symbol	Parameter	Conditions	V_{DD}	Min	Typ	Max	Unit
t _{PZH}	OFF-state to HIGH propagation delay	\bar{E} to Y _n , Z; see Figure 11	5 V	-	155	315	ns
			10 V	-	70	135	ns
		\bar{E} to Y _n , Z; see Figure 11	15 V	-	50	100	ns
t _{PZL}	OFF-state to LOW propagation delay		5 V	-	170	340	ns
			10 V	-	70	140	ns
			15 V	-	50	100	ns

11.1 Waveforms and test circuit



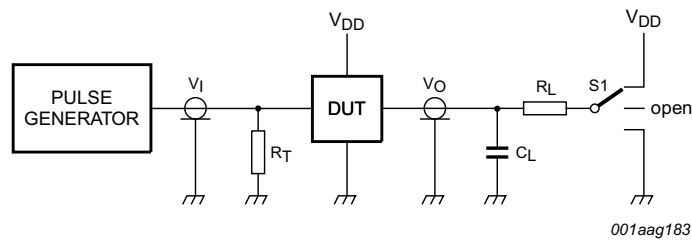


Measurement points are shown in [Table 9](#).
 V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 11. Enable and disable times

Table 9. Measurement points

Supply voltage	Input		Output		
V_{CC}	V_M	V_I	V_M	V_X	V_Y
5 V to 15 V	$0.5V_{DD}$	GND to V_{DD}	$0.5V_{DD}$	10%	90%



Test data is given in [Table 10](#).
 Definitions test circuit:
 R_T = termination resistance should be equal to output impedance Z_o of the pulse generator
 C_L = load capacitance including jig and probe capacitance
 R_L = load resistor
 $S1$ = test selection switch

Fig 12. Test circuit for measuring switching times

Table 10. Test data

Input				Load		S1 position				
Yn, Z	An and E-bar	t_r, t_f	V_M	C_L	R_L	t_{PHL} [1]	t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}	other
V_{DD} or V_{SS}	V_{DD} or V_{SS}	≤ 20 ns	$0.5V_{DD}$	50 pF	10 k Ω	V_{DD} or V_{SS}	V_{SS}	V_{SS}	V_{DD}	V_{SS}

[1] For Yn to Z or Z to Yn propagation delays, use V_{SS} . For An or to Yn or Z propagation delays, use V_{DD} .

11.2 Additional dynamic parameters

Table 11. Additional dynamic characteristics

$V_{SS} = 0\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.

Symbol	Parameter	Conditions	V_{DD}	Typ	Max	Unit	
THD	total harmonic distortion	see Figure 13; $R_L = 10\text{ k}\Omega$; $C_L = 15\text{ pF}$; channel ON; $V_I = 0.5V_{DD}$ (p-p); $f_i = 1\text{ kHz}$	5 V	[1]	0.25	-	%
			10 V	[1]	0.04	-	%
			15 V	[1]	0.04	-	%
$f_{(-3dB)}$	-3 dB frequency response	see Figure 14; $R_L = 1\text{ k}\Omega$; $C_L = 5\text{ pF}$; channel ON; $V_I = 0.5V_{DD}$ (p-p)	5 V	[1]	13	-	MHz
			10 V	[1]	40	-	MHz
			15 V	[1]	70	-	MHz
α_{iso}	isolation (OFF-state)	see Figure 15; $f_i = 1\text{ MHz}$; $R_L = 1\text{ k}\Omega$; $C_L = 5\text{ pF}$; channel OFF; $V_I = 0.5V_{DD}$ (p-p)	10 V	[1]	-50	-	dB
V_{ct}	crosstalk voltage	digital inputs to switch; see Figure 16; $R_L = 10\text{ k}\Omega$; $C_L = 15\text{ pF}$; \bar{E} or $A_n = V_{DD}$ (square-wave)	10 V		50	-	mV
Xtalk	crosstalk	between switches; see Figure 17; $f_i = 1\text{ MHz}$; $R_L = 1\text{ k}\Omega$; $V_I = 0.5V_{DD}$ (p-p)	10 V	[1]	-50	-	dB

[1] f_i is biased at $0.5 V_{DD}$; $V_I = 0.5V_{DD}$ (p-p).

Table 12. Dynamic power dissipation P_D

P_D can be calculated from the formulas shown; $V_{SS} = 0\text{ V}$; $t_r = t_f \leq 20\text{ ns}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.

Symbol	Parameter	V_{DD}	Typical formula for P_D (μW)	where:
P_D	dynamic power dissipation	5 V	$P_D = 1000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f_i = input frequency in MHz; f_o = output frequency in MHz; C_L = output load capacitance in pF; V_{DD} = supply voltage in V; $\Sigma(C_L \times f_o)$ = sum of the outputs.
		10 V	$P_D = 5500 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	
		15 V	$P_D = 15000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	

11.2.1 Test circuits

001aag129

Fig 13. Test circuit for measuring total harmonic distortion

001aag235

Fig 14. Test circuit for measuring frequency response

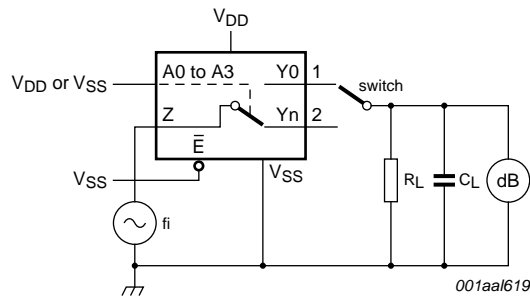
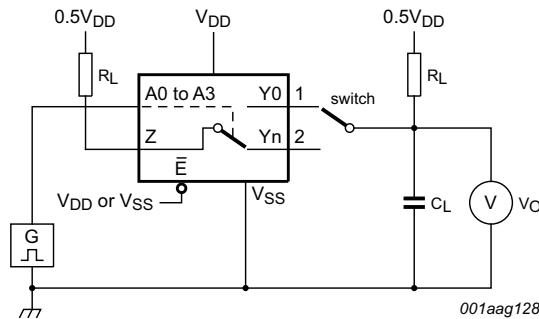
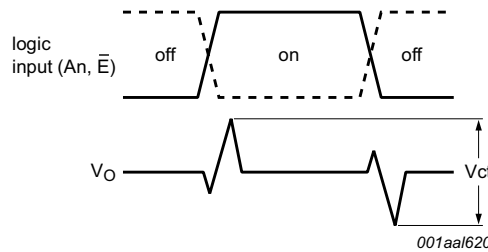


Fig 15. Test circuit for measuring isolation (OFF-state)

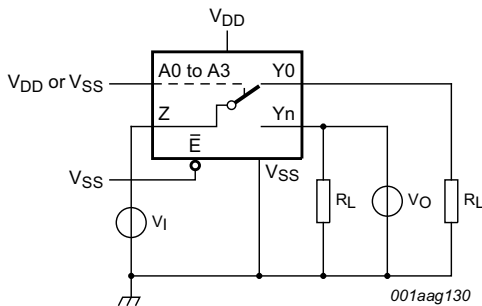


a. Test circuit

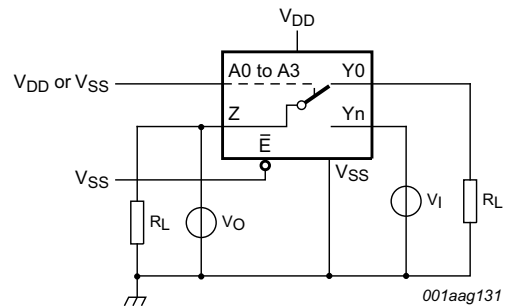


b. Input and output pulse definitions

Fig 16. Test circuit for measuring crosstalk voltage between digital inputs and switch



a. Switch closed condition



b. Switch open condition

Fig 17. Test circuit for measuring crosstalk between switches

12. Package outline

SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1

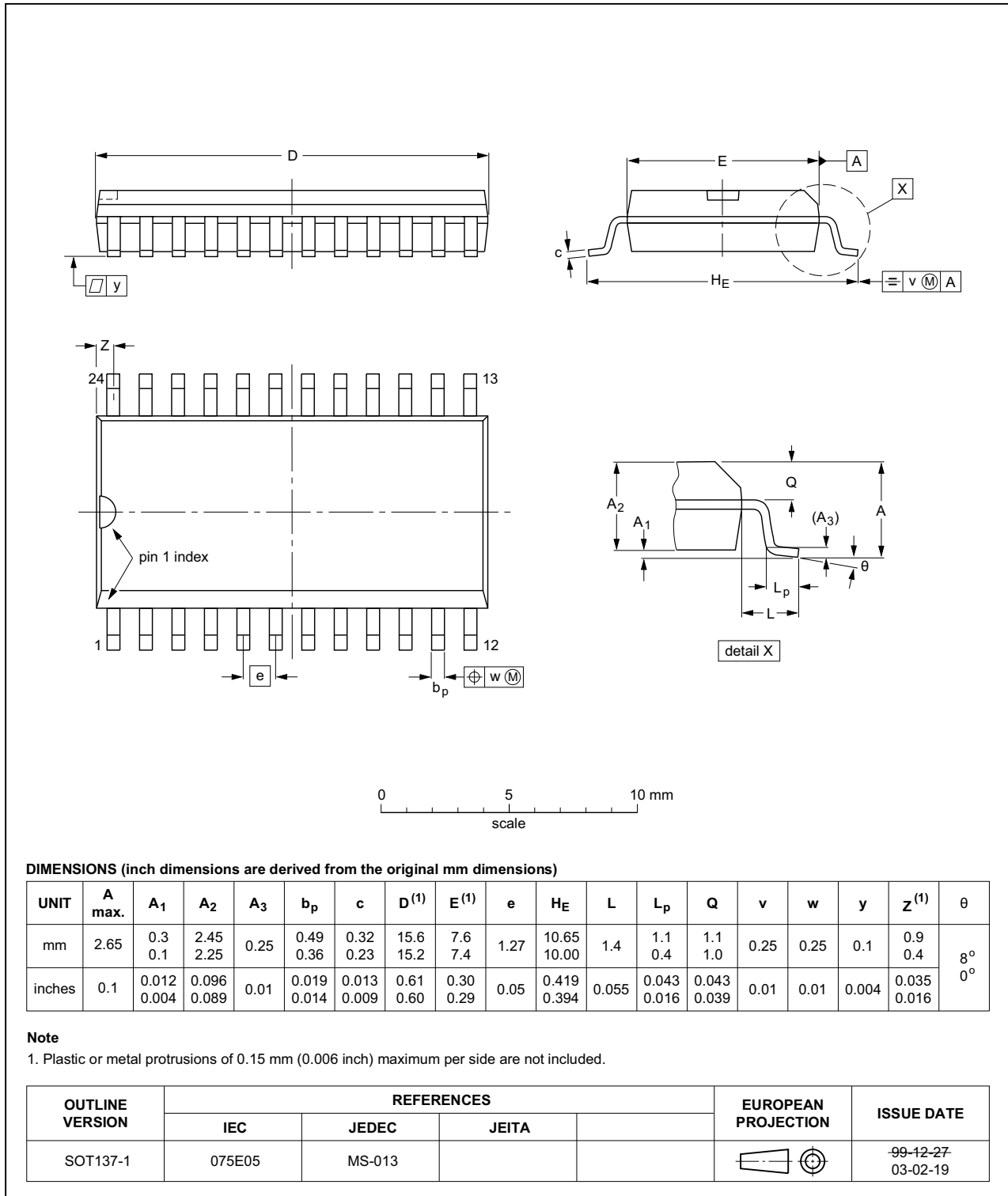


Fig 18. Package outline SOT137-1 (SO24)

13. Abbreviations

Table 13. Abbreviations

Acronym	Description
HBM	Human Body Model
ESD	ElectroStatic Discharge
MM	Machine Model
MIL	Military

14. Revision history

Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4067B-Q100 v.2	20140911	Product data sheet	-	HEF4067B-Q100 v.1
Modifications:	• Figure 16 : Test circuit modified			
HEF4067B-Q100 v.1	20130924	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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